JSR Lift off Photoresist  LP series

Single Layer Lift off resist

Single Layer (Negative tone)

LP-0008
Thickness: 2.5 - 4.0 µm

Simple process

- Ideal cross-section profile
  * Deep undercut shape can be easily obtained
- Simple and stable lithography process
  * One step exposure and good PCD/PED stability
- Good stripping property
  * Easily removed by various solvent
- Excellent thermal tolerance
  * PR profile was not changed after thermal treatment at 100 °C

Lift-off process

Lithography  Metal deposition  Stripping

LP-0008 Patterning Profile

Exposure dose

<table>
<thead>
<tr>
<th>Exposure dose</th>
<th>230 mJ/cm²</th>
<th>240 mJ/cm²</th>
<th>250 mJ/cm²</th>
<th>260 mJ/cm²</th>
<th>270 mJ/cm²</th>
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</thead>
<tbody>
<tr>
<td>0.8 µm</td>
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<td>2.4 µm</td>
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<td>1.3 µm</td>
<td>2.4 µm</td>
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<td>6.6 µm</td>
<td>4.7 µm</td>
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<tr>
<td>0.7 µm</td>
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<tr>
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<td>3.3 µm</td>
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Film Thickness: 2.5 µm
L/S: 20 µm / 20 µm